Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info: <u>ti.com/support</u>

Form/Declaration Type: Distribute - RoHS and IEC 62474 DB

Created on: **06/09/2022**

Details for "TLV7163318PDPQT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV7163318PDPQT	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DPQ 6	1.2x1.2x0.37	1.3

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB	
Yes	Yes	Yes	Yes	

Component Information

				Homogeneous Material Level		Component Level			
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm		
Bond Wire									
Precious Metals	Gold	7440-57-5	0.016951	100	1000000	1.279581	12796		
Sub-Total			0.016951	100	1000000	1.279581	12796		
Die Attach Adhesive	Die Attach Adhesive								
Other Nonferrous Metals and Alloys	Titanium Dioxide	13463-67-7	0.00062	3.000242	30002	0.046802	468		
Thermoplastics	Ероху	85954-11-6	0.020045	96.999758	969998	1.513139	15131		
Sub-Total			0.020665	100	1000000	1.559941	15599		
Lead Frame			-						
Copper and Its Alloys	Copper	7440-50-8	0.24899	35.57	355700	18.795528	187955		
Copper and Its Alloys	Iron	7439-89-6	0.38059	54.37	543700	28.729628	287296		
Copper and Its Alloys	Phosphorus	7723-14-0	0.00084	0.12	1200	0.063409	634		
Nickel and Its Alloys	Nickel	7440-02-0	0.00525	0.75	7500	0.396307	3963		
Other Inorganic Materials	Silica	7631-86-9	0.04802	6.86	68600	3.62489	36249		
Other Inorganic Materials	Sulfur	7704-34-9	0.00077	0.11	1100	0.058125	581		
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.0021	0.3	3000	0.158523	1585		
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	0.00427	0.61	6100	0.32233	3223		
Other Plastics and Rubber	Carbon	7440-44-0	0.00133	0.19	1900	0.100398	1004		
Precious Metals	Palladium	7440-05-3	0.00252	0.36	3600	0.190227	1902		
Thermoplastics	Ероху	85954-11-6	0.00532	0.76	7600	0.401591	4016		
Sub-Total			0.7	100	1000000	52.840956	528410		
Lead Frame Plating	Lead Frame Plating								
Nickel and Its Alloys	Nickel	7440-02-0	0.28536	95.12	951200	21.540993	215410		
Precious Metals	Gold	7440-57-5	0.00234	0.78	7800	0.17664	1766		
Precious Metals	Palladium	7440-05-3	0.0123	4.1	41000	0.928491	9285		
Sub-Total			0.3	100	1000000	22.646124	226461		
Mold Compound									
Other Inorganic Materials	Fused Silica	60676-86-0	0.168907	85.00005	850001	12.750296	127503		
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	0.009936	5.000151	50002	0.75004	7500		
Other Plastics and Rubber	Carbon Black	1333-86-4	0.000397	0.199785	1998	0.029968	300		
Thermoplastics	Ероху	85954-11-6	0.019474	9.800014	98000	1.470035	14700		
Sub-Total			0.198714	100	1000000	15.00034	150003		
Semiconductor Device									
Ceramics / Glass	Doped Silicon	7440-21-3	0.0884	100	1000000	6.673058	66731		
Sub-Total			0.0884	100	1000000	6.673058	66731		
Total			1.32473			100	1000000		

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

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For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/09/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.